

IN THE CLAIMS

1. – 6. (previously cancelled)

7. (previously presented) A method for fabricating an apparatus, the method comprising:

fabricating a thin-film resonator on a substrate; and

fabricating a bonding pad connected to said thin-film resonator, a portion of said bonding pad in contact with the substrate to form a Schottky diode.

8. (previously presented) The method recited in claim 7 wherein said bonding pad forms a plurality of Schottky diodes with the substrate.

9. (previously presented) The method recited in claim 7 wherein said bonding pad comprises a conductive material.

10. (previously presented) The method recited in claim 7 wherein said bonding pad comprises conductor selected from a group consisting of gold, nickel, and chrome.

11. (original) The method recited in claim 7 wherein said thin-film resonator comprises piezoelectric portion sandwiched by a bottom electrode and a top electrode.

12. (original) The method recited in claim 11 wherein the piezoelectric portion comprises Aluminum Nitride and said bottom and top electrodes comprises Molybdenum.

//

//

//